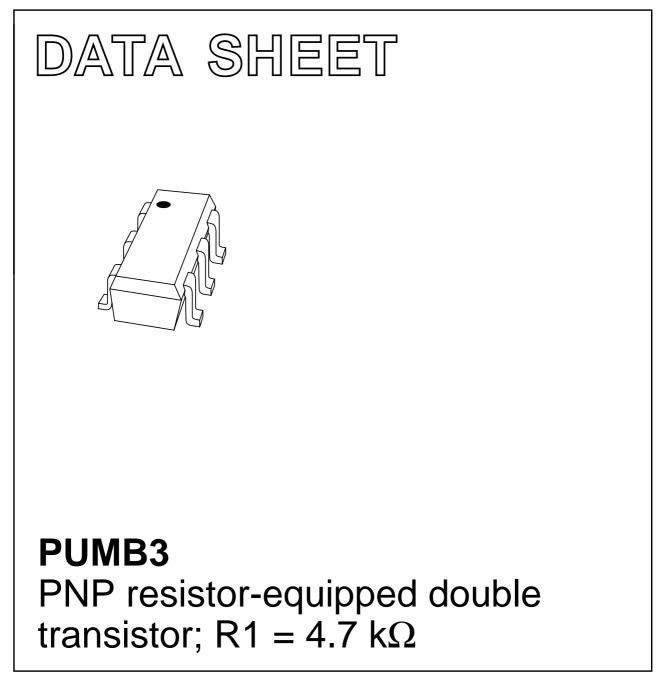
# DISCRETE SEMICONDUCTORS



Product specification

2001 Sep 19



### PUMB3

#### FEATURES

- Transistors with built-in bias resistor R1 (typ. 4.7 k $\Omega$ )
- No mutual interference between the transistors
- Simplification of circuit design
- Reduces number of components and board space.

#### APPLICATIONS

- General purpose switching and amplification
- Inverter and interface circuits
- Circuit driver.

#### DESCRIPTION

PNP resistor-equipped double transistor in an SC-88 (SOT363) plastic package.

#### MARKING

TYPE NUMBER	MARKING CODE <sup>(1)</sup>		
PUMB3	B5*		

#### Note

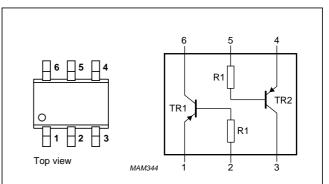
- 1. \* = p: Made in Hong Kong.
  - \* = t: Made in Malaysia.

#### PINNING

PIN		DESCRIPTION
1, 4	emitter	TR1; TR2
2, 5	base	TR1; TR2
6, 3	collector	TR1; TR2

#### QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	-50	V
I <sub>CM</sub>	peak collector current	-100	mA
TR1	PNP	_	_
TR2	PNP	_	_
R1	bias resistor	4.7	kΩ



# Fig.1 Simplified outline (SC-88; SOT363) and symbol.

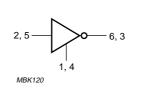


Fig.2 Equivalent inverter symbol.

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#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per transist	tor				
V <sub>CBO</sub>	collector-base voltage	open emitter	-	-50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	-50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	-10	V
VI	input voltage				
	positive		-	+10	V
	negative		-	-40	V
lo	output current (DC)		_	-100	mA
I <sub>CM</sub>	peak collector current		_	-100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	-	200	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C
Per device					
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	300	mW

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	416	K/W	

#### Note

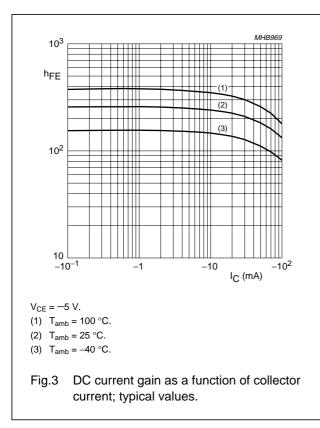
1. Transistor mounted on an FR4 printed-circuit board.

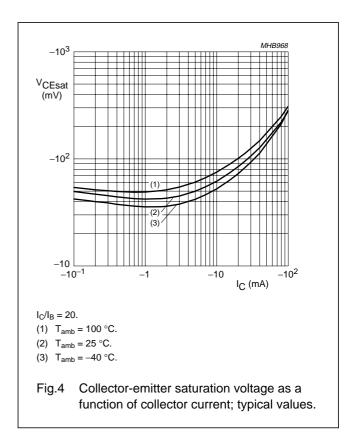
### PUMB3

#### CHARACTERISTICS

T<sub>amb</sub> = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per transist	or			•		
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = -50 \text{ V}; \text{ I}_{E} = 0$	-	-	-100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; \text{ I}_{B} = 0$	-	-	-1	μA
		$V_{CE} = -30 \text{ V}; \text{ I}_{B} = 0; \text{ T}_{j} = 150 ^{\circ}\text{C}$	-	-	-50	μA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = -5 V; I_C = 0$	-	-	-100	nA
h <sub>FE</sub>	DC current gain	$V_{CE} = -5 \text{ V}; \text{ I}_{C} = -1 \text{ mA}$	200	-	-	
V <sub>CEsat</sub>	saturation voltage	$I_{\rm C} = -5 \text{ mA}; I_{\rm B} = -0.25 \text{ mA}$	-	-	-100	mV
R <sub>1</sub>	input resistor		3.3	4.7	6.1	kΩ
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0; V_{CB} = -10 V;$ f = 1 MHz	-	-	3	pF

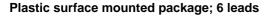


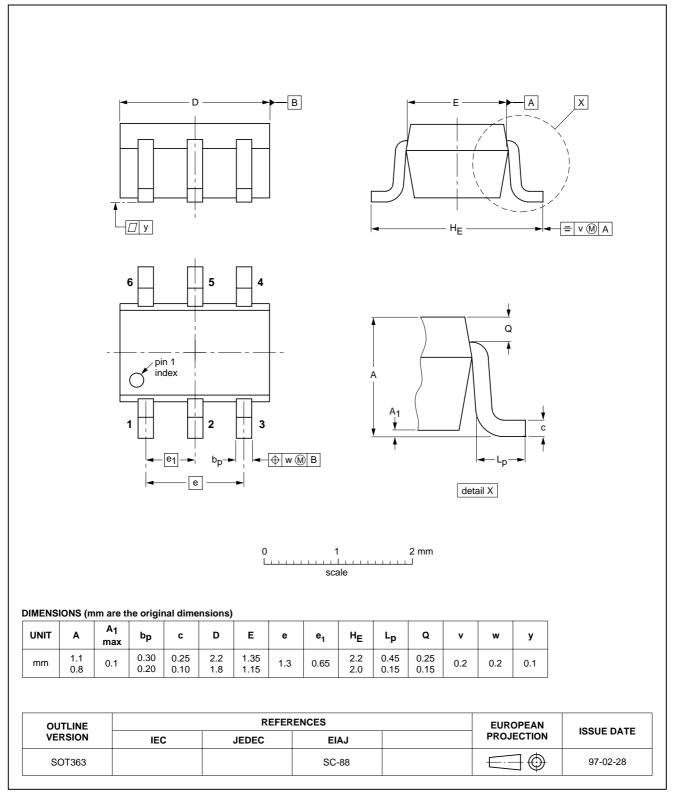


PUMB3

## PNP resistor-equipped double transistor; R1 = 4.7 k $\Omega$

#### PACKAGE OUTLINE





PUMB3

#### DATA SHEET STATUS

DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
Objective data	ata Development This data sheet contains data from the objective specification development. Philips Semiconductors reserves the right to cluster specification in any manner without notice.	
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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